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TITLE: SEMICONDUCTOR DEVICE

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ABSTRACT:

PROBLEM TO BE SOLVED: To provide a semiconductor device in which projecting and

recessing parts can be formed on the surface of a wire-bonding electrode with a simple method and which has a wire-bonding electrode part which is resistant against a bonding shock by selectively forming element isolating insulating films at the lowermost part of the wire-bonding electrode.

SOLUTION: An element isolating insulating films 2a are selectively formed at the lowermost part of a wire-bonding electrode 5. Thus, a semiconductor substrate 1 and an element isolating insulating films 2a, constituted of materials different from the semiconductor substrate 1, constitute the lowermost part. Thus, absorption force for absorbing the bonding shock added at the time of wire bonding becomes large, so that the semiconductor substrate 1 is prevented from being damaged or the occurrence of a crack in the semiconductor substrate 1. Consequently, the semiconductor device in which the projecting and recessing parts can be formed on the surface of the wire-bonding electrode with a simple method and having the wire-bonding electrode part which is resistant against the bonding shock can be provided.

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